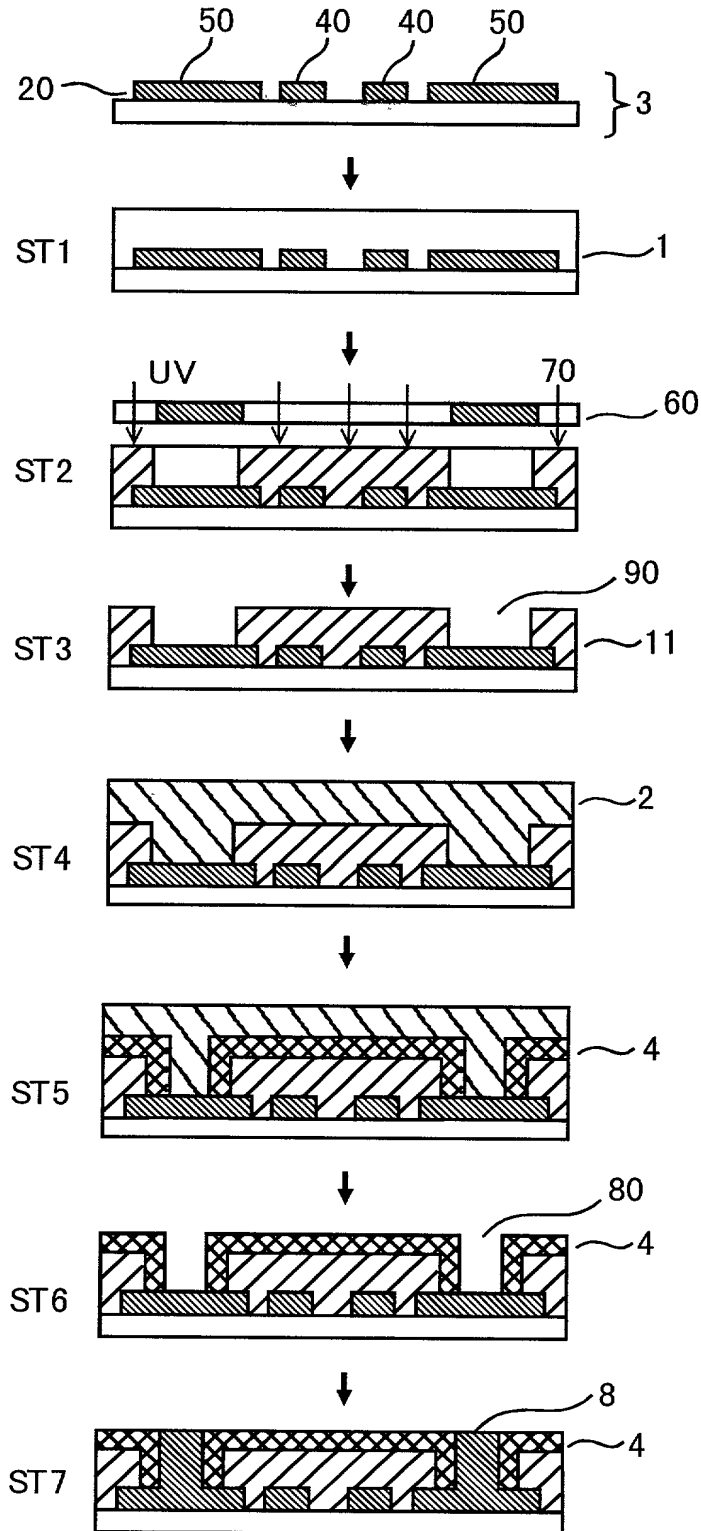
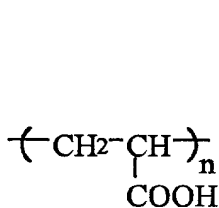


Fig. 1

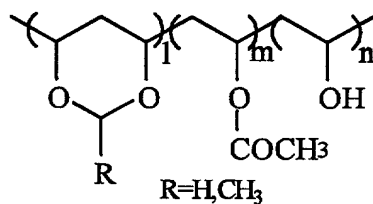


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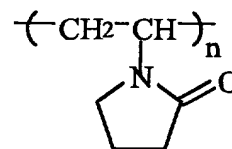
Fig.2



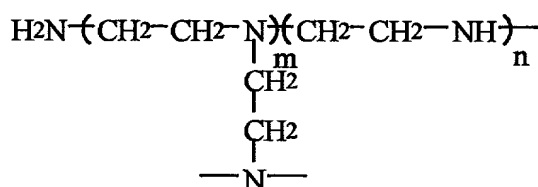
polyacrylic acid



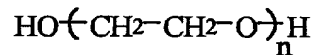
polyvinyl acetal



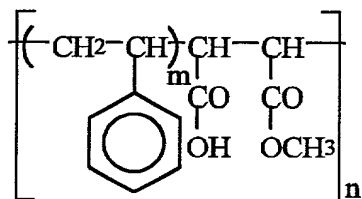
polyvinyl pyrrolidone



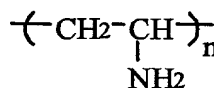
polyethyleneimine



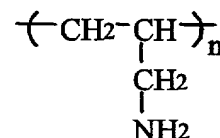
polyethylene oxide



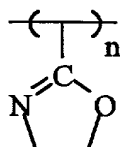
styrene-maleic acid copolymer



polyvinylamine resin

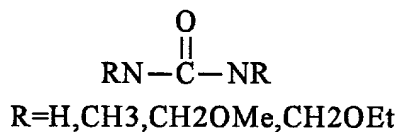


polyallylamine

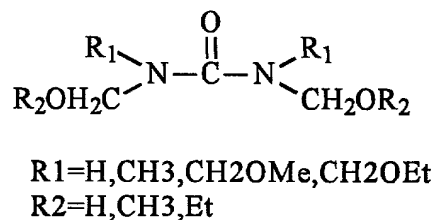


oxazoline group-containing
water-soluble resin

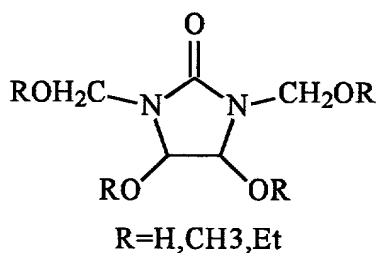
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[illegible]

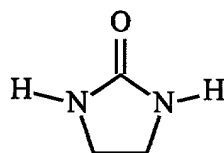
ureaderivatives



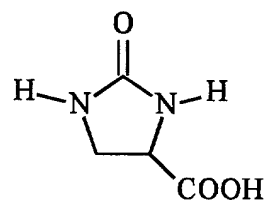
alkoxymethylurea



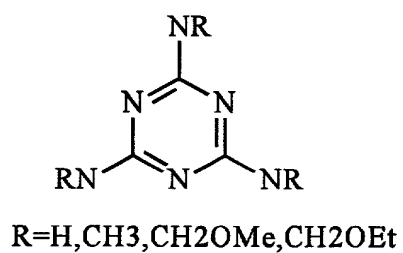
N-alkoxyethyleneurea



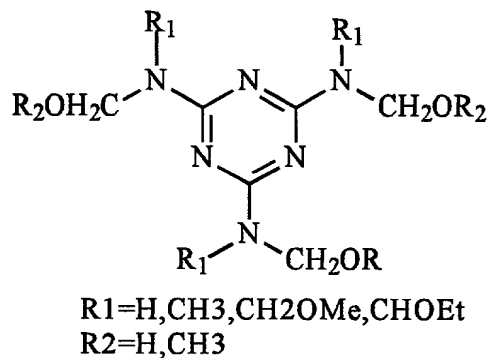
ethyleneurea



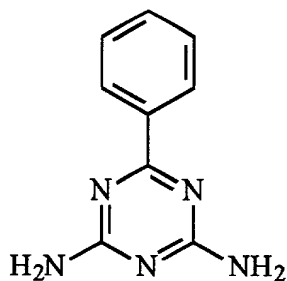
ethyleneureacarboxylic
acid



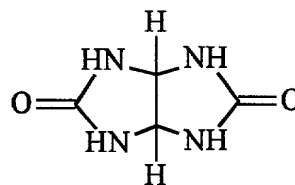
melamine derivatives



alkoxymethylmelamine derivatives



benzoguanamine



glycoluril

Fig.4

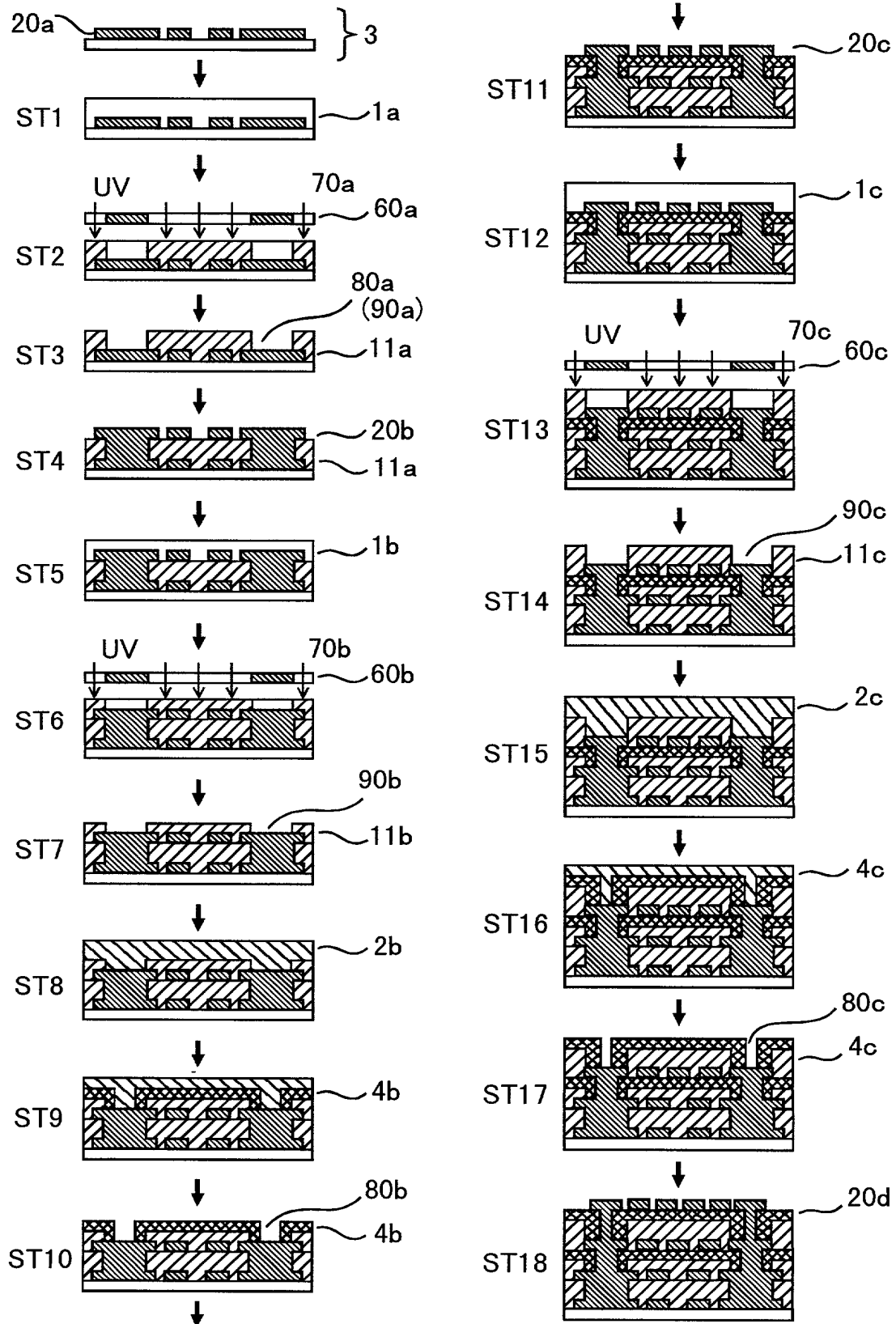
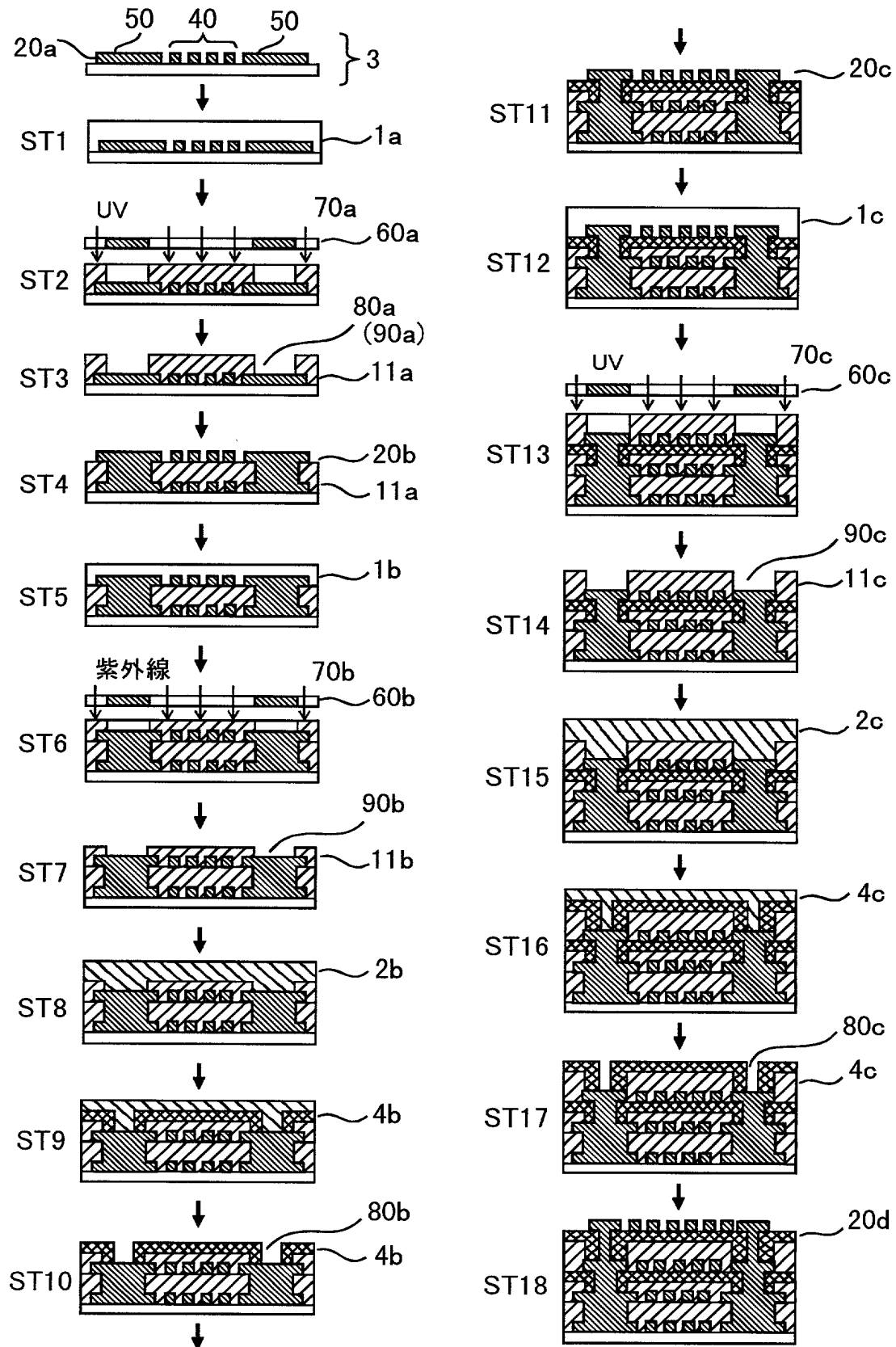


Fig.5



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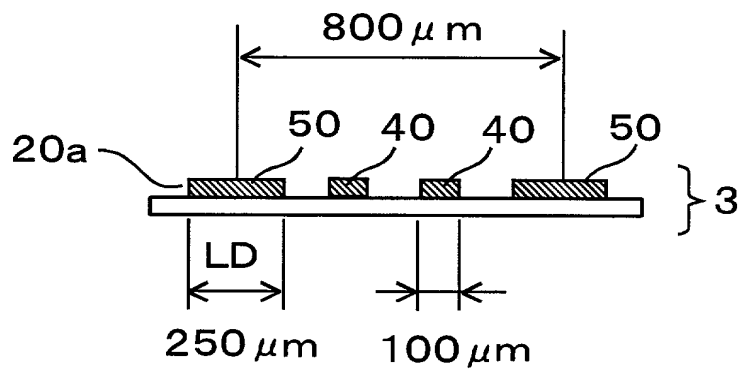
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Fig.7

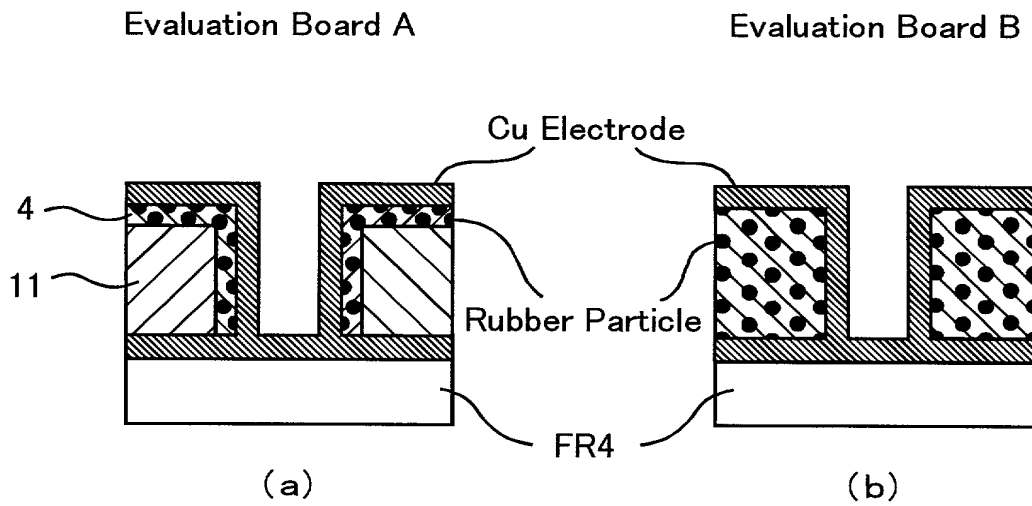
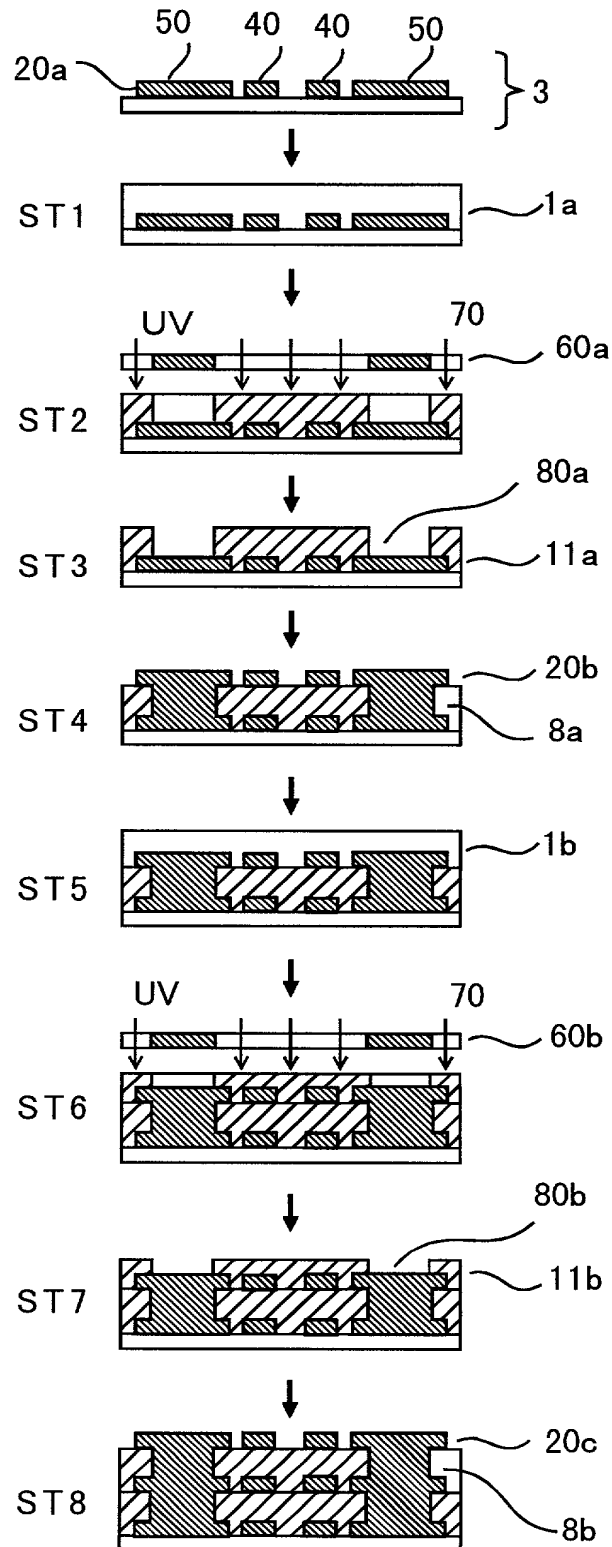


Fig.8
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Table 1

Condition	Diameter of Via-Hole
Non Heat Treatment	150 μ m
120°C/60min	130 μ m
130°C/30min	100 μ m
140°C/30min	70 μ m

Table 2

Condition	Diameter of Via-Hole
Non Heat Treatment	150 μ m
110°C/10min	120 μ m
110°C/20min	100 μ m
110°C/30min	80 μ m
135°C/40min	40 μ m

Table 3

Condition	Diameter of Via-Hole
Non Heat Treatment	150 μ m
110°C/15min	120 μ m
120°C/15min	100 μ m
130°C/15min	80 μ m
135°C/20min	45 μ m

Table 4

Condition	Diameter of Via-Hole
Non Heat Treatment	100 μ m
120°C/30min	96 μ m
130°C/30min	90 μ m
140°C/30min	83 μ m

Table 5

Sample	Dielectric Constant 〔 1kHz 25°C 〕	Thermal Expansion 〔 Vertical 80~120°C 〕	Peel Strength 〔 90° Peel 25°C 〕
Evaluation Board A	4.5	40ppm	980kg/cm
Evaluation Board B	4.8	55ppm	970kg/cm